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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Betano	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc65a-04i-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CXX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CXX uses a Harvard architecture, in which, program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture where program and data may be fetched from the same memory using the same bus. Separating program and data busses further allows instructions to be sized differently than 8-bit wide data words. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A twostage pipeline overlaps fetch and execution of instructions (Example 3-1). Consequently, all instructions execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The PIC16C61 addresses 1K x 14 of program memory. The PIC16C62/62A/R62/64/64A/R64 address 2K x 14 of program memory, and the PIC16C63/R63/65/65A/R65 devices address 4K x 14 of program memory. The PIC16C66/67 address 8K x 14 program memory. All program memory is internal.

The PIC16CXX can directly or indirectly address its register files or data memory. All special function registers including the program counter are mapped in the data memory. The PIC16CXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of "special optimal situations" makes programming with the PIC16CXX simple yet efficient, thus significantly reducing the learning curve. The PIC16CXX device contains an 8-bit ALU and working register (W). The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift, and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register), the other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending upon the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. Bits C and DC operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

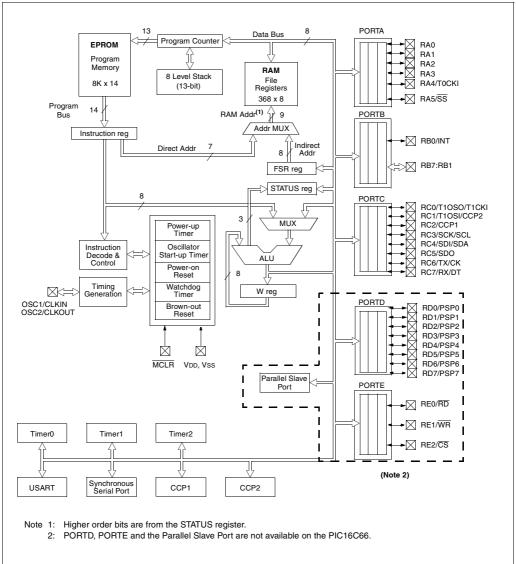


FIGURE 3-4: PIC16C66/67 BLOCK DIAGRAM

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clock and instruction execution flow is shown in Figure 3-5.

3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. GOTO) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

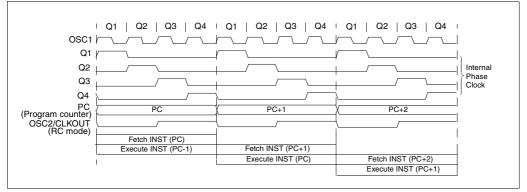
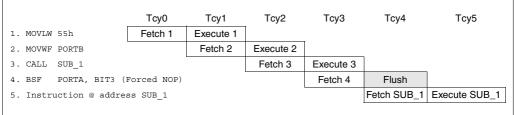


FIGURE 3-5: CLOCK/INSTRUCTION CYCLE

EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

4.2.2.5 PIR1 REGISTER

Applicable Devices													
61 62	62A	R62	63	R63	64	64 <i>F</i>	R64	65	65A	R65	5 66	67	
This periph	0				IS 1	the	indiv	idu	al fl	ag	bits	for	the

Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-16: PIR1 REGISTER FOR PIC16C62/62A/R62 (ADDRESS 0Ch)

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0				
_	-	_	_	SSPIF	CCP1IF	TMR2IF	TMR1IF	R = Readable bit			
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset			
bit 7-6:	Reserved:	Always ma	aintain thes	e bits clear.				LI			
bit 5-4:	Unimplem	ented: Rea	ad as '0'								
bit 3:	 SSPIF: Synchronous Serial Port Interrupt Flag bit 1 = The transmission/reception is complete (must be cleared in software) 0 = Waiting to transmit/receive 										
bit 2:	CCP1IF: CCP1 Interrupt Flag bit Capture Mode 1 = A TMR1 register capture occurred (must be cleared in software) 0 = No TMR1 register capture occurred Compare Mode 1 = A TMR1 register compare match occurred (must be cleared in software) 0 = No TMR1 register compare match occurred (must be cleared in software) 0 = No TMR1 register compare match occurred PWM Mode Unused in this mode										
bit 1:	TMR2IF: TMR2 to PR2 Match Interrupt Flag bit 1 = TMR2 to PR2 match occurred (must be cleared in software) 0 = No TMR2 to PR2 match occurred										
bit 0:	TMR1IF: TMR1 Overflow Interrupt Flag bit 1 = TMR1 register overflow occurred (must be cleared in software) 0 = No TMR1 register overflow occurred										
globa	Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.										

SWITCHING PRESCALER ASSIGNMENT 7.3.1

The prescaler assignment is fully under software control, i.e., it can be changed "on the fly" during program execution.

Note:	To avoid an unintended device RESET, the
	following instruction sequence (shown in
	Example 7-1) must be executed when
	changing the prescaler assignment from
	Timer0 to the WDT. This precaution must
	be followed even if the WDT is disabled.

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

	1)	BSF	STATUS, RPO	;Bank 1
Lines 2 and 3 do NOT have to	2)	MOVLW	b'xx0x0xxx'	;Select clock source and prescale value of
be included if the final desired	3)	MOVWF	OPTION_REG	;other than 1:1
prescale value is other than 1:1.	4)	BCF	STATUS, RPO	;Bank 0
If 1:1 is final desired value, then a temporary prescale value is	5)	CLRF	TMR0	;Clear TMR0 and prescaler
set in lines 2 and 3 and the final	6)	BSF	STATUS, RP1	;Bank 1
prescale value will be set in lines	7)	MOVLW	b'xxxx1xxx'	;Select WDT, do not change prescale value
10 and 11.	8)	MOVWF	OPTION_REG	;
	9)	CLRWDT		;Clears WDT and prescaler
	10)	MOVLW	b'xxxx1xxx'	;Select new prescale value and WDT
	11)	MOVWF	OPTION_REG	;
	12)	BCF	STATUS, RPO	;Bank 0

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 7-2.

EXAMPLE 7-2: CHANGING PRESCALER (WDT → TIMER0)

CLRWDT ;Clear WDT and prescaler BSF STATUS, RP0 ;Bank 1 MOVLW b'xxxx0xxx' ;Select TMR0, new prescale value and clock source MOVWF OPTION REG ; BCF STATUS, RPO ;Bank 0

TABLE 7-1: **REGISTERS ASSOCIATED WITH TIMER0**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h, 101h	TMR0	Timer0	module's r	egister						xxxx xxxx	uuuu uuuu
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE ⁽¹⁾	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h, 181h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	_	PORTA Data Direction Register ⁽¹⁾					11 1111	11 1111	

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

FIGURE 10-1: CCP1CON REGISTER (ADDRESS 17h) / CCP2CON REGISTER (ADDRESS 1Dh)

U-0	U-0 R/W-0 R	/W-0 R/W-0	R/W-0	R/W-0	R/W-0	
—	- CCPxX CC	CPxY CCPxM3	CCPxM2	CCPxM1	CCPxM0	R = Readable bit
bit7					bit0	W = Writable bit
						U = Unimplemented bit, read as '0'
						- n =Value at POR reset
bit 7-6:	Unimplemented: F	Poad as '0'				
	•					
bit 5-4:	CCPxX:CCPxY: PV	VM Least Significa	ant bits			
	Capture Mode Unused					
	Compare Mode					
	Unused					
	PWM Mode					
	These bits are the t	wo LSbs of the P	NM duty cy	cle. The eig	ht MSbs are	found in CCPRxL.
bit 3-0:	CCPxM3:CCPxM0	: CCPx Mode Sele	ect bits			
	0000 = Capture/Co	•		k module)		
	0100 = Capture mo		•			
	0101 = Capture mo		•			
	0110 = Capture mo	· ·	0 0			
	1000 = Compare m	· ·	• •	CCPxIF is	set)	
	1001 = Compare m		•		,	
	•		•		,	is set, CCPx pin is unaffected)
	•		al event (CC	PxIF bit is s	et; CCP1 res	ets TMR1; CCP2 resets TMR1)
	11xx = PWM mode	9				

10.1 Capture Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RC2/CCP1 (Figure 10-2). An event is defined as:

- · Every falling edge
- · Every rising edge
- · Every 4th rising edge
- Every 16th rising edge

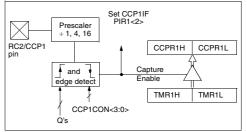
An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

10.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1 pin is configured as an
	output, a write to PORTC can cause a cap-
	ture condition.

FIGURE 10-2: CAPTURE MODE OPERATION BLOCK DIAGRAM



10.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work consistently.

10.1.3 SOFTWARE INTERRUPT

When the Capture event is changed, a false capture interrupt may be generated. The user should clear enable bit CCP1IE (PIE1<2>) to avoid false interrupts and should clear flag bit CCP1IF following any such change in operating mode.

TABLE 13-9:	STATUS BITS AND THEIR SIGNIFICANCE FOR
	PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

POR	BOR	то	PD	
0	х	1	1	Power-on Reset
0	x	0	x	Illegal, TO is set on a Power-on Reset
0	x	x	0	Illegal, PD is set on a Power-on Reset
1	0	x	x	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR reset during normal operation
1	1	1	0	MCLR reset during SLEEP or interrupt wake-up from SLEEP

Legend: x = unknown, u = unchanged

TABLE 13-10: RESET CONDITION FOR SPECIAL REGISTERS ON PIC16C61/62/64/65

	Program Counter	STATUS	PCON ⁽²⁾
Power-on Reset	000h	0001 1xxx	0 -
MCLR reset during normal operation	000h	000u uuuu	u-
MCLR reset during SLEEP	000h	0001 0uuu	u-
WDT Reset	000h	0000 luuu	u-
WDT Wake-up	PC + 1	uuu0 0uuu	u-
Interrupt wake-up from SLEEP	PC + 1 ⁽¹⁾	uuul 0uuu	u-

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

2: The PCON register is not implemented on the PIC16C61.

TABLE 13-11: RESET CONDITION FOR SPECIAL REGISTERS ON PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

	Program Counter	STATUS	PCON
Power-on Reset	000h	0001 1xxx	0x
MCLR reset during normal operation	000h	000u uuuu	uu
MCLR reset during SLEEP	000h	0001 0uuu	uu
WDT Reset	000h	0000 luuu	uu
Brown-out Reset	000h	0001 luuu	u0
WDT Wake-up	PC + 1	uuu0 0uuu	uu
Interrupt wake-up from SLEEP	PC + 1 ⁽¹⁾	uuu1 0uuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

FIGURE 13-11: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

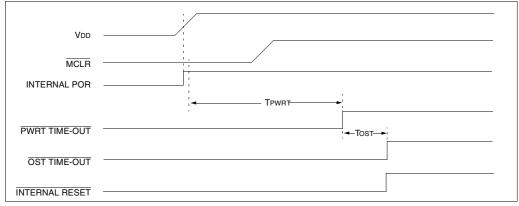


FIGURE 13-12: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

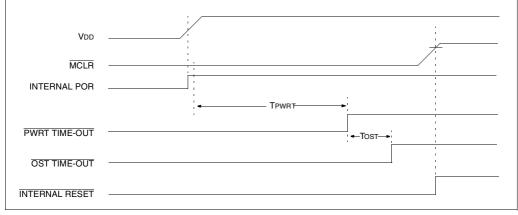
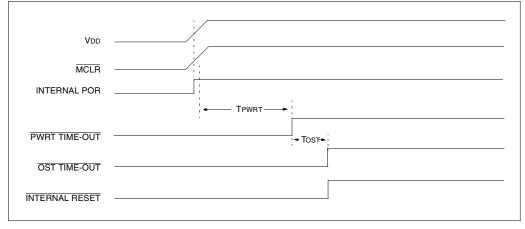
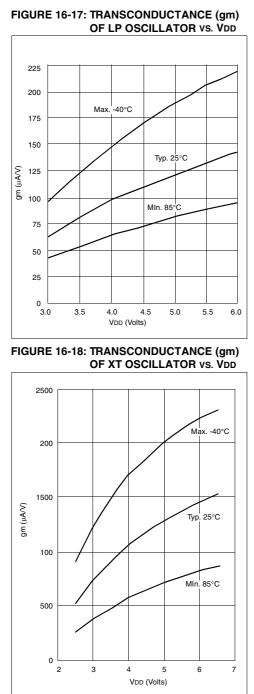


FIGURE 13-13: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)



Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67





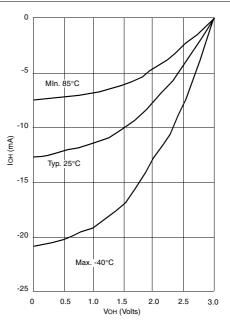
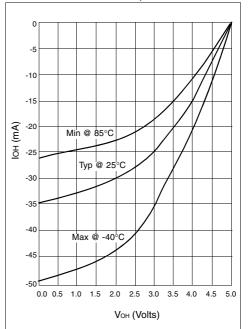


FIGURE 16-20: IOH VS. VOH, VDD = 5V



Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



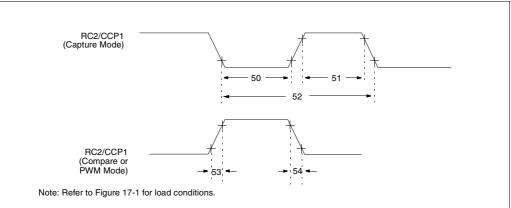


TABLE 17-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Parameter No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*			No Prescaler		0.5TCY + 20	_	-	ns	
		input low time	With Prescaler	PIC16 C 62/64	10	_		ns	
				PIC16 LC 62/64	20	_	_	ns	
51*	TccH	CCP1	No Prescaler		0.5Tcy + 20	_	_	ns	
		input high time	With Prescaler	PIC16 C 62/64	10	_	_	ns	
				PIC16 LC 62/64	20	_	_	ns	
52*	TccP	CCP1 input period			<u>3Tcy + 40</u> N	-	-	ns	N = prescale value (1,4 or 16)
53	TccR	CCP1 output rise time	9	PIC16 C 62/64	_	10	25	ns	
				PIC16 LC 62/64	_	25	45	ns	
54	TccF	CCP1 output fall time		PIC16 C 62/64	_	10	25	ns	
				PIC16LC62/64	_	25	45	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



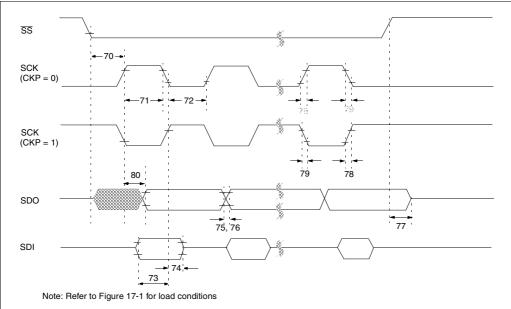


TABLE 17-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70	TssL2scH, TssL2scL	\overline{SS} ↓ to SCK↓ or SCK↑ input	Тсү	—	—	ns	
71	TscH	SCK input high time (slave mode)	Tcy + 20	_	_	ns	
72	TscL	SCK input low time (slave mode)	Tcy + 20	_	_	ns	
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	_	—	ns	
75	TdoR	SDO data output rise time		10	25	ns	
76	TdoF	SDO data output fall time		10	25	ns	
77	TssH2doZ	SS↑ to SDO output hi-impedance	10	_	50	ns	
78	TscR	SCK output rise time (master mode)		10	25	ns	
79	TscF	SCK output fall time (master mode)	_	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge	_	_	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

18.3 DC Characteristics: PIC16C62A/R62/64A/R64-04 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-10 (Commercial, Industrial, Extended) PIC16C62A/R62/64A/R64-20 (Commercial, Industrial, Extended) PIC16LC62A/R62/64A/R64-04 (Commercial, Industrial)

DC CH	ARACTERISTICS	$\begin{array}{llllllllllllllllllllllllllllllllllll$								
Param No.	Characteristic	Sym	Min	тур †	Мах	Units	Conditions			
110.	Input Low Voltage									
	I/O ports	VIL								
D030	with TTL buffer	VIL	Vss	-	0.15VDD	v	For entire VDD range			
D030A			VSS	_	0.13VDD	v	$4.5V \le VDD \le 5.5V$			
D031	with Schmitt Trigger buffer		Vss	-	0.2VDD	v				
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2VDD	v				
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	v	Note1			
	Input High Voltage					-				
	I/O ports	Viн		-						
D040	with TTL buffer		2.0	-	VDD	v	$4.5V \leq VDD \leq 5.5V$			
D040A			0.25VDD	-	Vdd	V	For entire VDD range			
			+ 0.8V				, , , , , , , , , , , , , , , , , , ,			
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd	v	For entire VDD range			
D042	MCLR		0.8VDD	-	Vdd	V				
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1			
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V				
D070	PORTB weak pull-up current	I PURB	50	250	400	μA	VDD = 5V, VPIN = VSS			
	Input Leakage Current (Notes 2, 3)									
D060	I/O ports	lı∟	-	-	±1	μA	$Vss \leq VPIN \leq VDD, Pin at hi-impedance$			
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \leq VPIN \leq VDD$			
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP			
							osc configuration			
	Output Low Voltage									
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C			
D080A			-	-	0.6	v	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C			
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	v	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C			
D083A			-	-	0.6	v	IOL = 1.2 mA, VDD = 4.5 V, -40°C to +125°C			

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 19-5: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

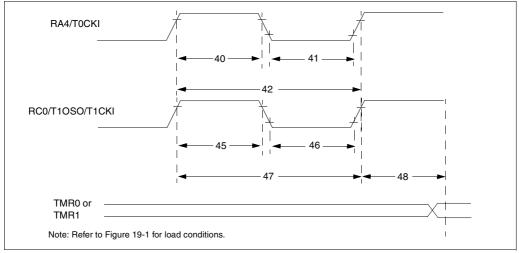


TABLE 19-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5TCY + 20	_		ns	Must also meet
				With Prescaler	10	_	_	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	_	—	ns	Must also meet
				With Prescaler	10	—	—	ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	_	ns	N = prescale value (2, 4,, 256)
45*	Tt1H	T1CKI High Time	Synchronous, F	Prescaler = 1	0.5TCY + 20	-	_	ns	Must also meet
		0	Synchronous,	PIC16 C 6X	15	_	_	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	—	ns	-
			Asynchronous	PIC16 C 6X	30	—	-	ns	
				PIC16 LC 6X	50	—	-	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, F	Prescaler = 1	0.5TCY + 20	_	—	ns	Must also meet
			Synchronous,	PIC16 C 6X	15	—	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 6X	25	-	—	ns	
			Asynchronous	PIC16 C 6X	30	_	—	ns	
				PIC16 LC 6X	50	-	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 6X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	-	—	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 6X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 6X	60	_	—	ns	
				PIC16 LC 6X	100	-	—	ns	
	Ft1	Timer1 oscillator inp (oscillator enabled b			DC	-	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tir	ner increment	2Tosc	—	7Tosc	—	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	B62	63	B63	64	64A	R64	65	65A	B65	66	67

		Standa	rd Operat	ing C	ondition	s (unle	ss otherwise stated)			
		Operatir	ng temper	ature	-40°	Ć≤T	$A \le +125^{\circ}C$ for extended,			
	RACTERISTICS				-40°	C ≤T	$A \le +85^{\circ}C$ for industrial and			
	RACIERISTICS				0°C	≤ 1	$A \le +70^{\circ}C$ for commercial			
		Operating voltage VDD range as described in DC spec Section 20.1 and Section 20.2								
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions			
No.				†						
	Output High Voltage									
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°С to +85°С			
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°С to +125°С			
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С			
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°С to +125°С			
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin			
	Capacitive Loading Specs on Out- put Pins									
D100	OSC2 pin	Cosc ₂	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.			
D101	All I/O pins and OSC2 (in RC mode)	Cio	-	-	50	pF				
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF				

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

20.5 <u>Timing Diagrams and Specifications</u>

FIGURE 20-2: EXTERNAL CLOCK TIMING

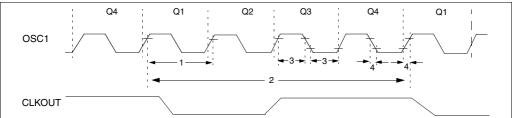


TABLE 20-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC	I	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	-	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250		—	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
		Oscillator Period	250		_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3*	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR,	External Clock in (OSC1) Rise or	—	_	25	ns	XT oscillator
	TosF	Fall Time	—	—	50	ns	LP oscillator
			_	_	15	ns	HS oscillator

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

21.0 ELECTRICAL CHARACTERISTICS FOR PIC16CR63/R65

Absolute Maximum Ratings (†)

Ambient temperature under bias	55°C to +125°C
Ambient temperature under bias Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	
Voltage on VDD with respect to VSS	-0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0V to +14V
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	
Maximum current out of Vss pin	
Maximum current into VDD pin	
Maximum current into VDD pin Input clamp current, Iiκ (VI < 0 or VI > VDD) Output clamp current, Ioκ (VO < 0 or VO > VDD) Maximum output current sunk by any I/O pin	±20 mA
Output clamp current, Iok (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	
Maximum output current sourced by any I/O pin	
Maximum current sunk by PORTA, PORTB, and PORTE (Note 3) (combined)	
Maximum current sourced by PORTA, PORTB, and PORTE (Note 3) (combined)	
Maximum current sunk by PORTC and PORTD (Note 3) (combined)	$\sim 200 \mathrm{mA}$
Maximum current sourced by PORTC and PORTD (Note 3) (combined)	
Note 1. Dever discipation is calculated as follows: Ddia VDD x (100 X 100)	

- **Note 1:** Power dissipation is calculated as follows: Pdis = $VDx \{IDD \SigmaIOH\} + \Sigma (VDD VOH) \times IOH\} + \Sigma (VOI \times IOL)$
- Note 2: Voltage spikes below Vss at the MCLR/VPP pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "fow" level to the MCLR/VPP pin rather than pulling this pin directly to Vss.
- Note 3: PORTD and PORTE not available on the P(C16CR63.

† NOTICE: Stresses above those listed under "Absolute Maximum Patings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

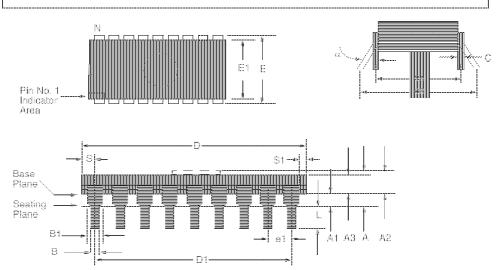
TABLE 21-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16CR63-04 PIC16CR65-04	PIC16CR63-10 PIC16CR65-10	PIC16CR63-20 PIC16CR65-20	PIC16LCR63-04 PIC16LCR65-04	JW Devices
RC		VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IRD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 5.5V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
ХТ	VDD: 4.0V to 5:5V IDP: -5 mA max. at 5.5V IPD: -16 µA max. at 4V Freq: 4 MHz max	Vod: 4.5V to 5.5V Idd: 2.7 mA typ. at 5.5V IPd: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 5.5V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V
	IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	IPD 1.5 μA typ. at 4.5V Freq: 10 MHz max.	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.		IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 5.5V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 3.0V to 5.5V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 5.5V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

24.6 18-Lead Ceramic CERDIP Dual In-line with Window (300 mil) (JW)

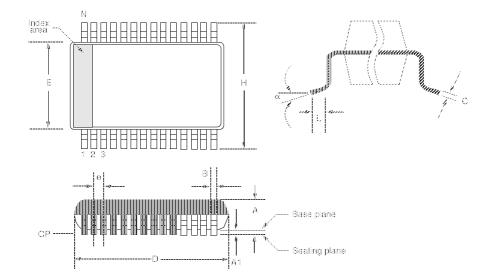
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Pa	ckage Group: (Ceramic CERDIP	Dual In-Line (C	DP)			
		Millimeters		Inches				
Symbol	Min	Max	Notes	Min	Max	Notes		
α	0°	10°		0°	10°			
А	_	5.080		_	0.200			
A1	0.381	1.778		0.015	0.070			
A2	3.810	4.699		0.150	0.185			
A3	3.810	4.445		0.150	0.175			
В	0.355	0.585		0.014	0.023			
B1	1.270	1.651	Typical	0.050	0.065	Typical		
С	0.203	0.381	Typical	0.008	0.015	Typical		
D	22.352	23.622		0.880	0.930			
D1	20.320	20.320	Reference	0.800	0.800	Reference		
E	7.620	8.382		0.300	0.330			
E1	5.588	7.874		0.220	0.310			
e1	2.540	2.540	Reference	0.100	0.100	Reference		
eA	7.366	8.128	Typical	0.290	0.320	Typical		
eB	7.620	10.160		0.300	0.400			
L	3.175	3.810		0.125	0.150			
Ν	18	18		18	18			
S	0.508	1.397		0.020	0.055			
S1	0.381	1.270		0.015	0.050			

24.10 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Packag	e Group: Plasti	c SSOP		
		Millimeters			Inches	
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
А	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
В	0.250	0.380		0.010	0.015	
С	0.130	0.220		0.005	0.009	
D	10.070	10.330		0.396	0.407	
E	5.200	5.380		0.205	0.212	
е	0.650	0.650	Reference	0.026	0.026	Reference
Н	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
Ν	28	28		28	28	
CP	-	0.102		-	0.004	

APPENDIX F: PIC16/17 MICROCONTROLLERS

F.1 PIC12CXXX Family of Devices

		PIC12C508	PIC12C509	PIC12C671	PIC12C672
lock	Maximum Frequency of Operation (MHz)	4	4	4	4
emory	EPROM Program Memory	512 x 12	1024 x 12	1024 x 14	2048 x 14
emory	Data Memory (bytes)	25	41	128	128
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
eripherals	A/D Converter (8-bit) Channels		_	4	4
	Wake-up from SLEEP on pin change	Yes	Yes	Yes	Yes
	I/O Pins	5	5	5	5
	Input Pins	1	1	1	1
atures	Internal Pull-ups	Yes	Yes	Yes	Yes
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Number of Instructions	33	33	35	35
	Packages	8-pin DIP, SOIC	8-pin DIP, SOIC	8-pin DIP, SOIC	8-pin DIP, SOIC

All PIC12C5XX devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC12C5XX devices use serial programming with data pin GP1 and clock pin GP0.

F.2 PIC14C000 Family of Devices

		PIC14C000
Clock	Maximum Frequency of Operation (MHz)	20
Memory	EPROM Program Memory (x14 words)	4K
	Data Memory (bytes)	192
	Timer Module(s)	TMR0 ADTMR
Peripherals	Serial Port(s) (SPI/I ² C, USART)	I ² C with SMBus Support
Features	Slope A/D Converter Channels	8 External; 6 Internal
	Interrupt Sources	11
	I/O Pins	22
	Voltage Range (Volts)	2.7-6.0
	In-Circuit Serial Programming	Yes
	Additional On-chip Features	Internal 4MHz Oscillator, Bandgap Reference,Temperature Sensor, Calibration Factors, Low Voltage Detector, SLEEP, HIBERNATE, Comparators with Programmable References (2)
	Packages	28-pin DIP (.300 mil), SOIC, SSOP

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